

**500 Volt, 1.5Ω HEXFET**

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required.

The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.

**Product Summary**

Part Number	BV <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
IRFY430CM	500V	1.5Ω	4.5A

**Features**

- Hermetically Sealed
- Electrically Isolated
- Simple Drive Requirements
- Ease of Paralleling
- Ceramic Eyelets

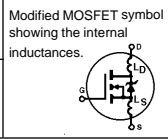
**Absolute Maximum Ratings**

	Parameter	IRFY430CM	Units
I <sub>D</sub> @ V <sub>GS</sub> =10V, T <sub>C</sub> = 25°C	Continuous Drain Current	4.5	A
I <sub>D</sub> @ V <sub>GS</sub> =10V, T <sub>C</sub> = 100°C	Continuous Drain Current	2.8	
I <sub>DM</sub>	Pulsed Drain Current ①	18	
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Max. Power Dissipation	75	W
	Linear Derating Factor	0.6	W/K ⑤
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
E <sub>AS</sub>	Single Pulse Avalanche Energy ②	280	mJ
I <sub>AR</sub>	Avalanche Current ①	4.5	A
E <sub>AR</sub>	Repetitive Avalanche Energy ①	7.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	3.5	V/ns
T <sub>J</sub>	Operating Junction	-55 to 150	°C
T <sub>stg</sub>	Storage Temperature Range		
	Lead Temperature	300 (0.063 in (1.6mm) from case for 10 sec)	
	Weight	4.3 (typical)	g

# IRFY430CM Device

## Electrical Characteristics @ T<sub>J</sub> = 25°C (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	500	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1.0mA
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	—	0.78	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1.0mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-State Resistance	—	—	1.5	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 2.8A <sup>④</sup>
		—	—	1.8		V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
g <sub>fs</sub>	Forward Transconductance	1.5	—	—	S (S)	V <sub>DS</sub> ≥ 15V, I <sub>DS</sub> = 2.8A <sup>④</sup>
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	—	—	25	μA	V <sub>DS</sub> = 0.8 x max. rating, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 0.8 x max. rating V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C
I <sub>GSS</sub>	Gate-to-Source Leakage Forward	—	—	100	nA	V <sub>GS</sub> = 20V
I <sub>GSS</sub>	Gate-to-Source Leakage Reverse	—	—	-100		V <sub>GS</sub> = -20V
Q <sub>g</sub>	Total Gate Charge	19.8	—	29.5	nC	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A
Q <sub>gs</sub>	Gate-to-Source Charge	2.2	—	4.6		V <sub>DS</sub> = Max. Rating x 0.5
Q <sub>gd</sub>	Gate-to-Drain ('Miller') Charge	5.5	—	19.7		see figures 5 and 13
t <sub>d(on)</sub>	Turn-On Delay Time	—	—	35	ns	V <sub>DD</sub> = 250V, I <sub>D</sub> = 4.5A, R <sub>G</sub> = 7.5, V <sub>GS</sub> = 10V  see figure 10
t <sub>r</sub>	Rise Time	—	—	30		
t <sub>d(off)</sub>	Turn-Off Delay Time	—	—	55		
t <sub>f</sub>	Fall Time	—	—	30		
L <sub>D</sub>	Internal Drain Inductance	—	8.7	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
L <sub>S</sub>	Internal Source Inductance	—	8.7	—		Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
C <sub>iss</sub>	Input Capacitance	—	6.0	—	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V f = 1.0MHz. see figure 5
C <sub>oss</sub>	Output Capacitance	—	135	—		
C <sub>rss</sub>	Reverse Transfer Capacitance	—	65	—		



## Source-Drain Diode Ratings and Characteristics

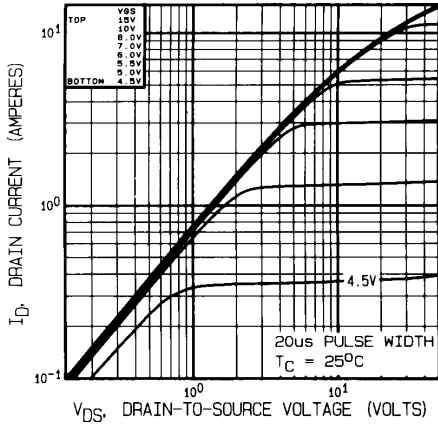
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	4.5	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
I <sub>SM</sub>	Pulse Source Current (Body Diode) <sup>①</sup>	—	—	18		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.4	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 4.5A, V <sub>GS</sub> = 0V <sup>④</sup>
t <sub>rr</sub>	Reverse Recovery Time	—	—	900	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 4.5A, di/dt ≤ 100 A/μs
Q <sub>RR</sub>	Reverse Recovery Charge	—	—	7.0	μC	V <sub>DD</sub> ≤ 50V <sup>④</sup>
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> .				



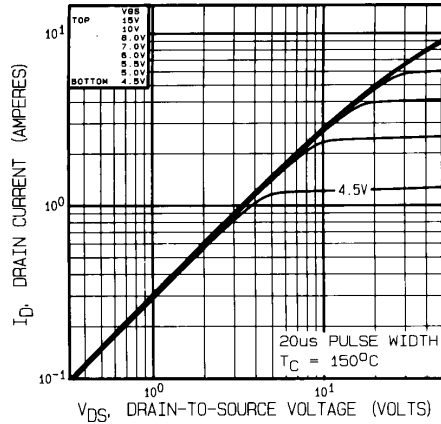
## Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R <sub>thJC</sub>	Junction-to-Case	—	—	1.67	K/W <sup>⑤</sup>	Typical socket mount Mounting surface flat, smooth
R <sub>thJA</sub>	Junction-to-Ambient	—	—	80		
R <sub>thCS</sub>	Case-to-Sink	—	0.21	—		

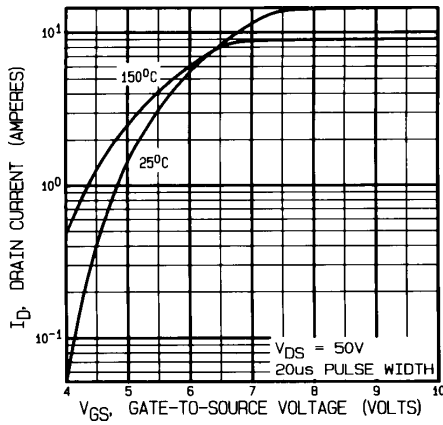
# IRFY430CM Device



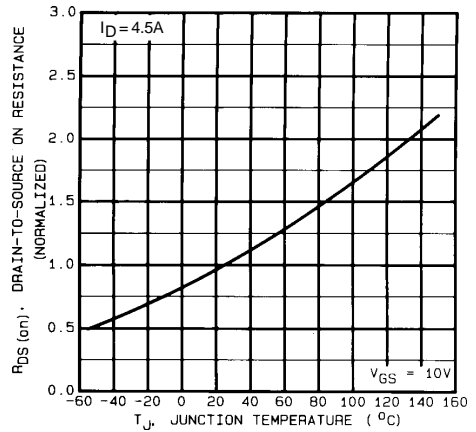
**Fig. 1 — Typical Output Characteristics**  
 $T_C = 25^\circ\text{C}$



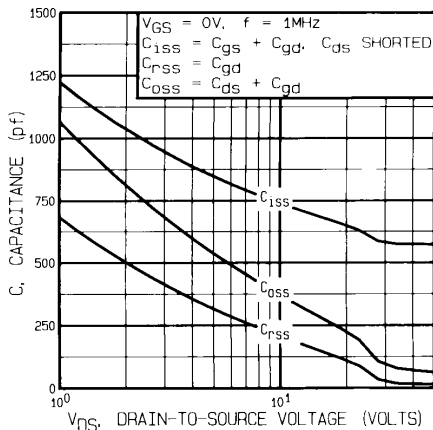
**Fig. 2 — Typical Output Characteristics**  
 $T_C = 150^\circ\text{C}$



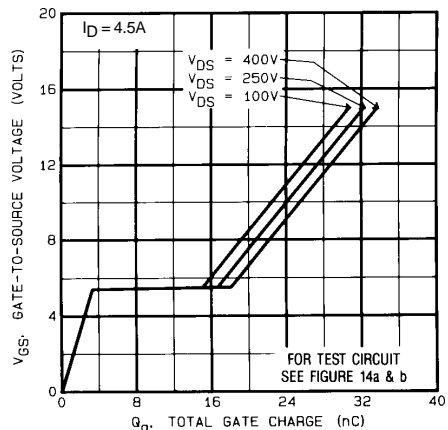
**Fig. 3 — Typical Transfer Characteristics**



**Fig. 4 — Normalized On-Resistance Vs. Temperature**

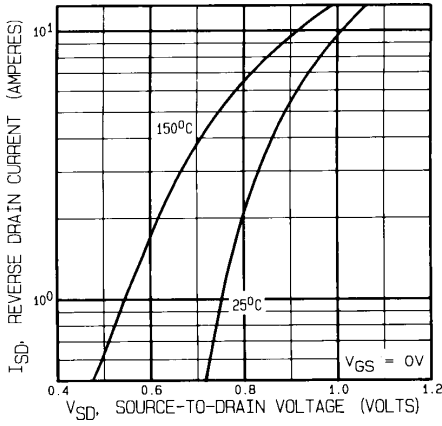


**Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage**

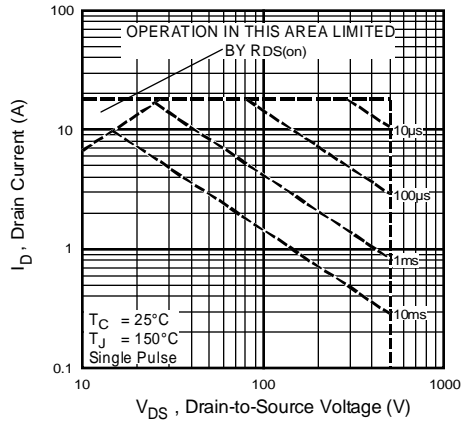


**Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage**

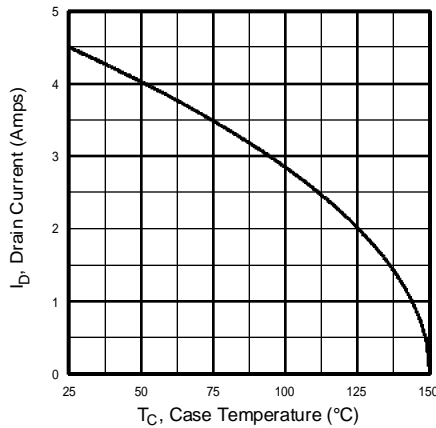
# IRFY430CM Device



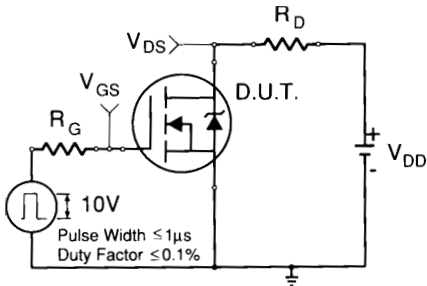
**Fig. 7 — Typical Source-to-Drain Diode Forward Voltage**



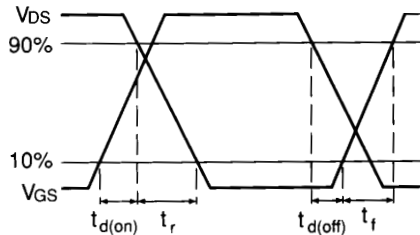
**Fig. 8 — Maximum Safe Operating Area**



**Fig. 9 — Maximum Drain Current Vs. Case Temperature**



**Fig. 10a — Switching Time Test Circuit**



**Fig. 10b — Switching Time Waveforms**

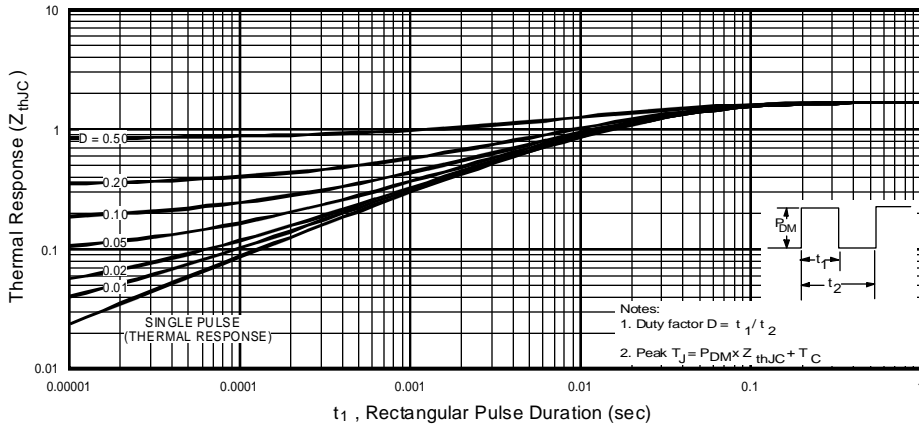


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

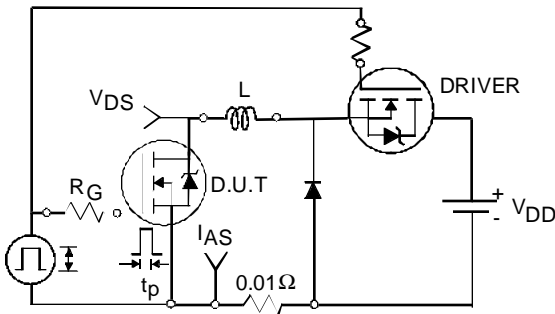


Fig. 12a — Unclamped Inductive Test Circuit

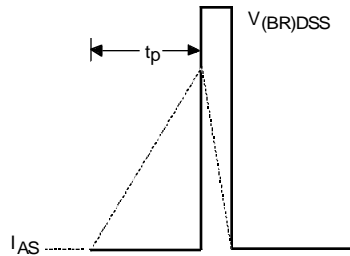


Fig. 12b — Unclamped Inductive Waveforms

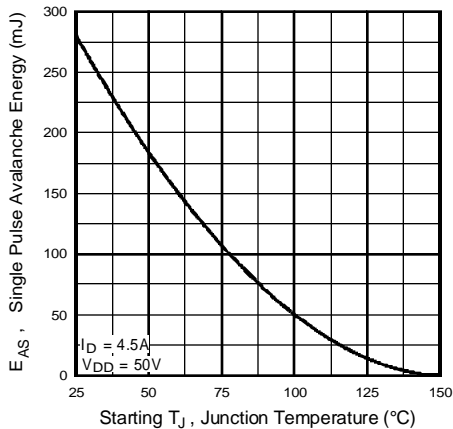


Fig. 12c — Max. Avalanche Energy vs. Current

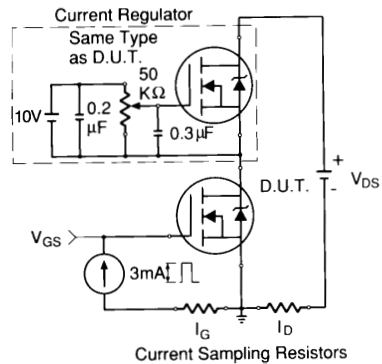


Fig. 13a — Gate Charge Test Circuit

# IRFY430CM Device

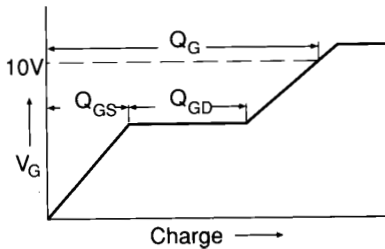
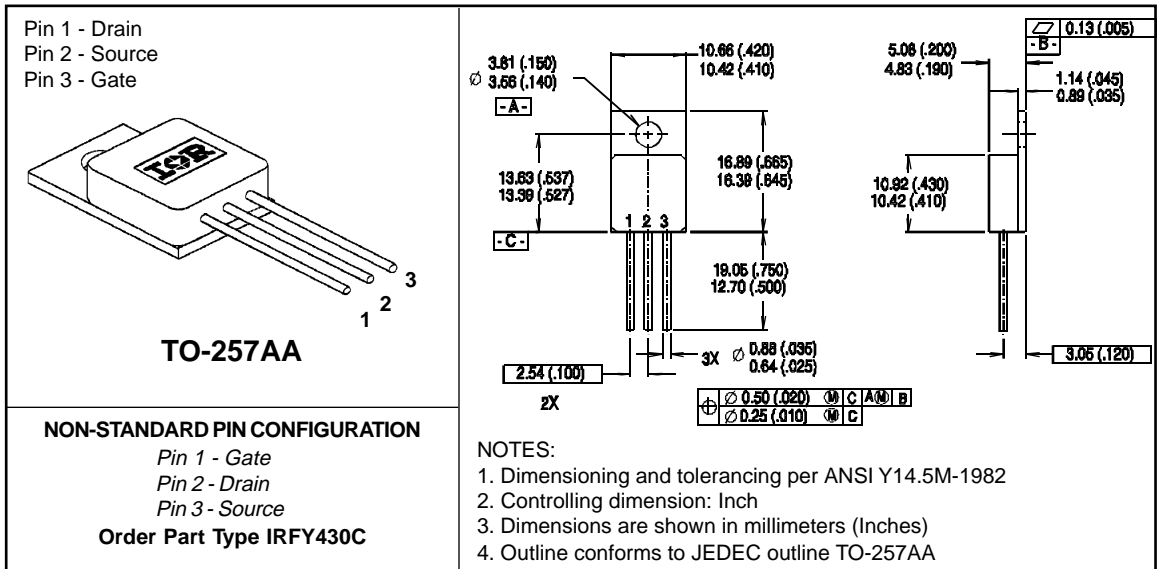


Fig. 13b — Basic Gate Charge Waveform

### Notes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature (see figure 11).
- ② @  $V_{DD} = 50V$ , Starting  $T_J = 25^\circ C$ ,  
 $E_{AS} = [0.5 * L * (I_D^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]$   
 Peak  $I_L = 4.5A$ ,  $V_{GS} = 10V$ ,  $25 \leq R_G \leq 200\Omega$  (figure 12)
- ③  $I_{SD} \leq 4.5A$ ,  $di/dt \leq 75A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤  $K/W = ^\circ C/W$        $W/K = W/^\circ C$

## Case Outline and Dimensions — TO-257AA



**CAUTION**

**BERYLLIA WARNING PER MIL-PRF-19500**

Packages containing beryllia shall not be ground, sandblasted, machined or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

# International **IR** Rectifier

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